

Amendments to the Specification

Please replace paragraph [0030], at page 8, lines 8-23 with the following amended paragraph:

Besides, referring to FIG.6, in a preferred embodiment of a PCB in accordance with the present invention, the solder mask 40 has a first area 404 and a second area 406. Unsheltered portion 263 of conductive pattern 26 can be formed with a base 265 and a tip 266. Area 404 is used to fully cover sheltered portion 261 of conductive pattern 26. Area 406 is used to surround base 265 of the unsheltered portion such that tip 266 of the unsheltered portion is exposed outside. Thereby, the cohere strength of unsheltered portion 263 and substrate 20 will be enhanced. The ion migration of the wiring of unsheltered portion 263 will be reduced. In other words, the wiring-density of unsheltered portion 263 will be increased since the pitch between the wiring of unsheltered portion is reduced.